



Eureka Microelectronics, Inc.

EK7102CG

DATA SHEET

120 Output Common LCD Driver



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120- Output LCD Common Driver IC

DESCRIPTION

The EK7102 is a 120-output common driver IC suitable for driving dot matrix LCD panels, and it is used in personal digital assistant, IA and handheld products. TCP and COG package is available for different demands, that COG package could be used for customer's system, and the TCP package which is ideal for substantially decreasing the size of the frame section of LCD module. When combined with Eureka's segment drivers, it can create a low power consuming, high resolution LCD Panel.

FEATURES

- Number of LCD drive outputs : 120
- Supply voltage for LCD drive : +15.0 to 40V
- Supply voltage for the logic system : +2.5 to +5.5V
- Shift clock frequency 4MHz max. at $V_{DD}=5V$

- Low power consumption
- Low output impedance
- Built-in 120-bit bi-directional shift register (divisible into 60 bits x 2)
- Available in a single mode (120-bit shift register) or in a dual mode (60-bit shift register x 2)
 1. $Y_1 \rightarrow Y_{120}$ Single mode
 2. $Y_{120} \rightarrow Y_1$ Single mode
 3. $Y_1 \rightarrow Y_{60}, Y_{61} \rightarrow Y_{120}$ Dual mode
 4. $Y_{120} \rightarrow Y_{61}, Y_{60} \rightarrow Y_1$ Dual mode

The above 4 shift directions are pin-selectable

- Shift register circuits are reset when $\overline{DISPOFF}$ active
- Package : TCP, COG available

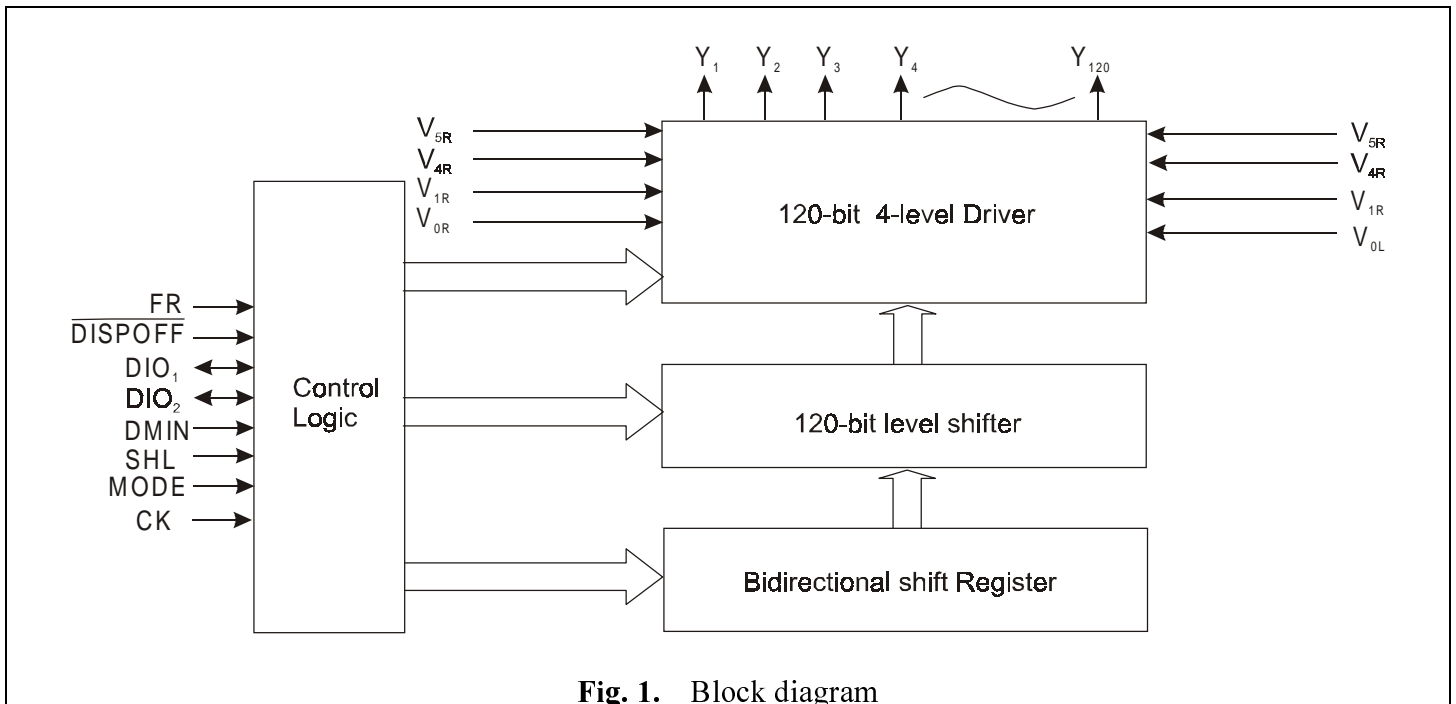


Fig. 1. Block diagram

PINNING INFORMATION

Table 1. Pin description

SYMBOL	I/O	DESCRIPTION
Y ₁ -Y ₁₂₀	O	LCD drive output
V _{0L}	—	Power supply for LCD drive
V _{0R}	—	Power supply for LCD drive
V _{1L} , V _{1R}	—	Power supply for LCD drive
V _{4L} , V _{4R}	—	Power supply for LCD drive
V _{5L} , V _{5R}	—	Power supply for LCD drive
V _{SS}	—	Ground (0V)
DIO ₂ , DIO ₁	I/O	Shift data input /output for shift register
FR	I	AC – converting signal input for LCD drive waveform
$\overline{\text{DISPOFF}}$	I	Control input to disable the display
SHL	I	Input for selecting the shift direction of shift register
MODE	I	Mode selection input
DMIN	I	Dual mode data input
CK	I	Shift clock input for shift register
V _{DD}	—	Power supply for logic system (+2.5 to 5.5 V)

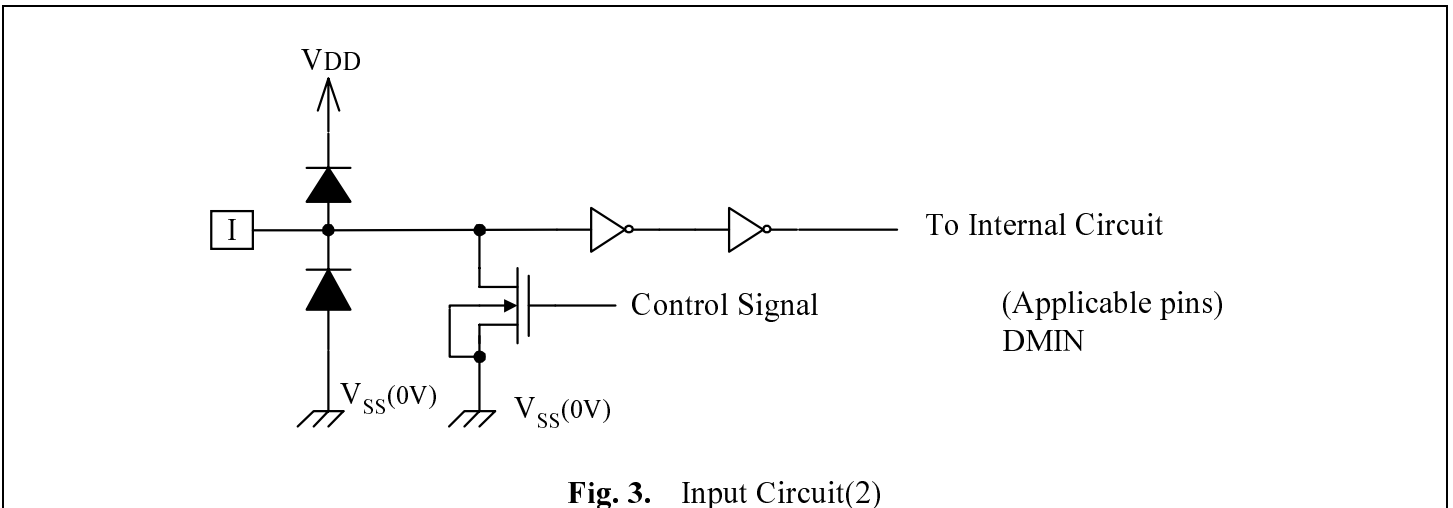
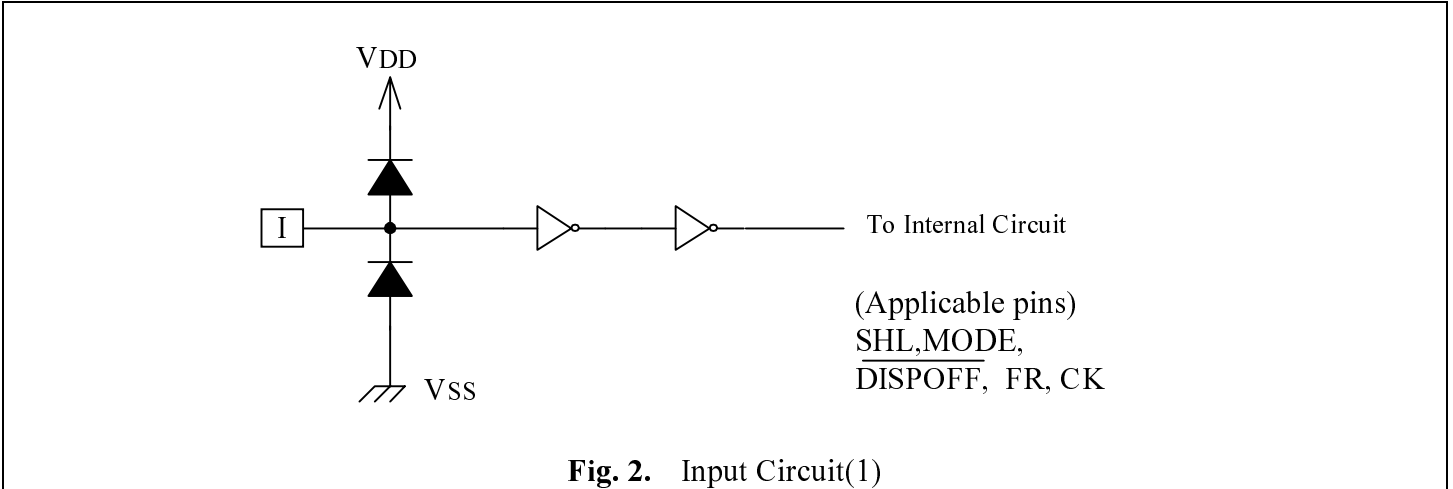
FUNCTIONAL DESCRIPTION

Table 2. Functional description

BLOCK	FUNCTION
Shift Register	At the falling edge of the CK signal the Shift Register shifts data from the data input pin, to the data output pin under control of the shift direction and mode setting received from the Control Logic block.
Level Shifter	The logic voltage signal is level-shifted to the LCD drive voltage level, and is output to the driver block.
4-Level Driver	Drives the LCD drive output pins from the shift register data, and selects one of 4 levels (V ₀ , V ₁ , V ₄ or V ₅) based on the FR and $\overline{\text{DISPOFF}}$ signals
Control Logic	Controls the shift register's direction of data shift and mode setting in response to SHL and MODE signal inputs

CIRCUIT DIAGRAMS

Input/Output Circuit



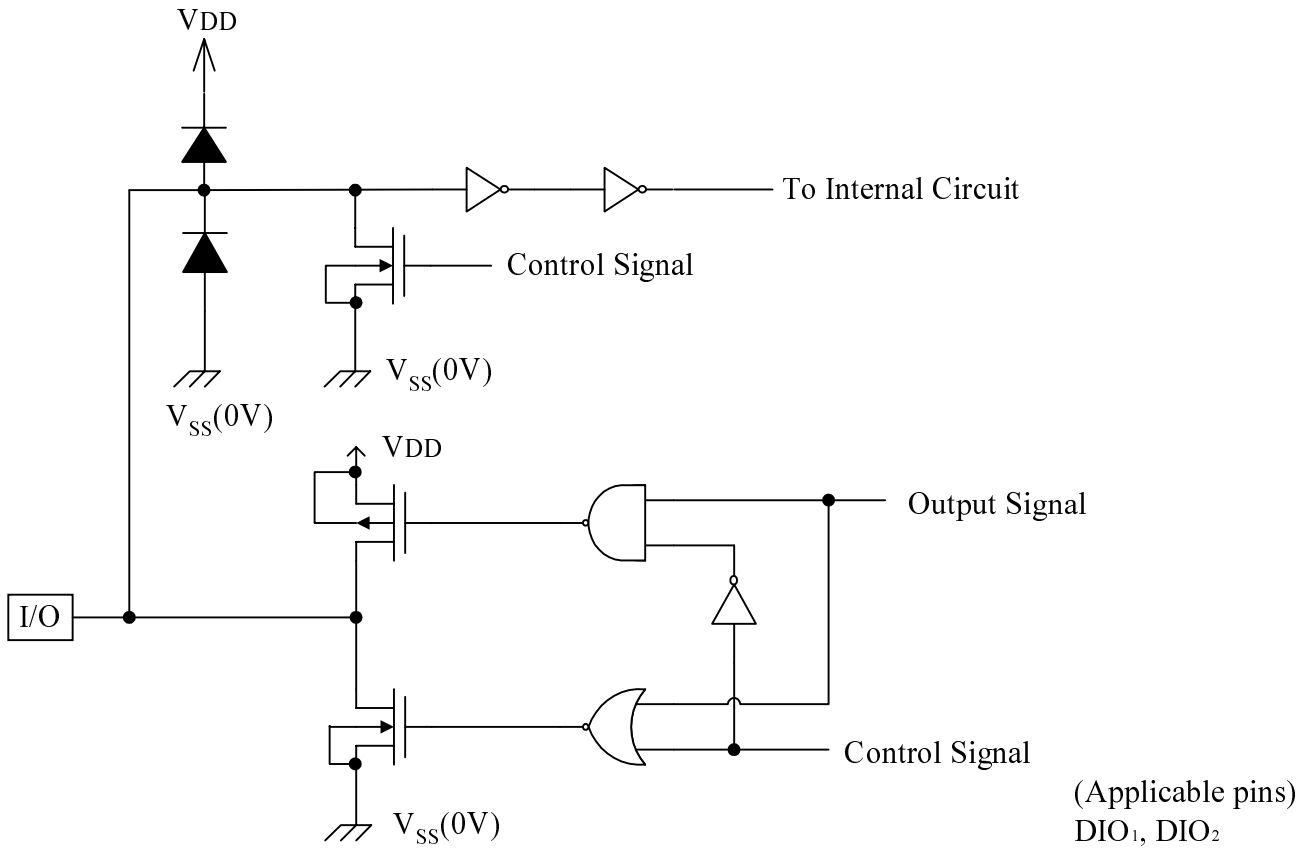


Fig. 4. Input/Output Circuit

(Applicable pins)
DIO₁, DIO₂

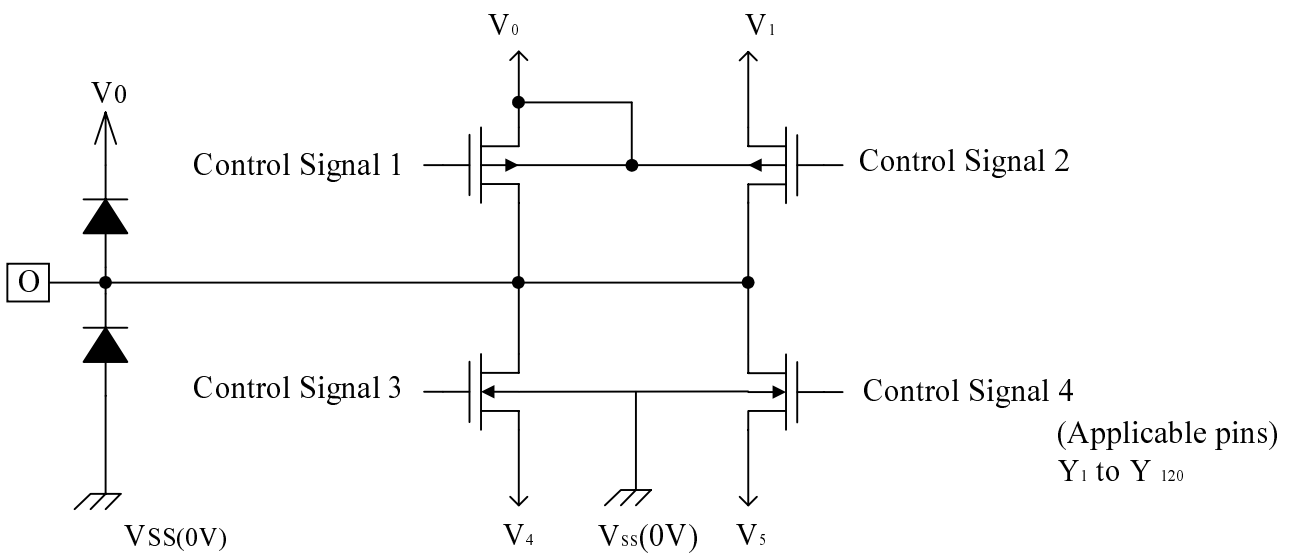


Fig. 5. LCD Driver Output Circuit

(Applicable pins)
Y₁ to Y₁₂₀

PIN DESCRIPTION

Table 3. Pin Description

Symbol	Function
V_{DD}	Logic system power supply pin, connected to +2.5 to +5.5 V
V_{SS}	Ground pin, connected to 0V.
V_{0L}, V_{0R} V_{1L}, V_{1R} V_{4L}, V_{4R} V_{5L}, V_{5R}	Power supply pins for LCD drive bias voltage <ul style="list-style-type: none"> • Normally use a resistor divider to set the bias voltage. • Set the voltages such that $V_{SS} \leq V_5 < V_4 < V_1 < V_0$. • V_{iL} and V_{iR} (i=0, 1, 4,5) must connect to an external power supply, and supply regular voltage which is assigned by specification for each power pin.
DIO_1	Shift data input/output pin for bi-directional shift register <ul style="list-style-type: none"> • Input pin when SHL=L, output pin when SHL=H. When SHL=L, DIO_1 is used as input pin, it will be pulled down and the data of DIO_1 will be latch at the falling edge of CK. When SHL=H, DIO_1 is used as output pin, it won't be pulled down and output data will after the falling edge of CK. • See also Table 5. .
DIO_2	Shift data input/output pin for bi-directional shift register <ul style="list-style-type: none"> • Input pin when SHL=H, output pin when SHL=L. • When SHL=H, DIO_2 is used as input pin, it will be pulled down and the data of DIO_2 will be latched at the falling edge of CK. When SHL=L, DIO_2 is used as output pin, it won't be pulled down and output data will change after the falling edge of CK. • See also Table 5. .
CK	Input clock pulse pin to shift the contents of the bi-directional shift register <ul style="list-style-type: none"> • DIO_1 or DIO_2 data is shifted at the falling edge of the clock pulse.
SHL	Direction selection for reading display data <ul style="list-style-type: none"> • When SHL is "L". Data is shifted from DIO_1 to Y_1, Y_1 to Y_2.....Y_{119} to Y_{120} and DIO_2. • When SHL is "H". Data is shifted from DIO_2 to Y_{120}, Y_{120} to Y_{119}.....Y_2 to Y_1 and DIO_1. • See also Table 5. .
$\overline{DISPOFF}$	Input pin to set all the outputs to non-select level, active low <ul style="list-style-type: none"> • The input signal is level-shifted from logic voltage level to LCD drive voltage level, and controls the LCD drive circuit. • When set to V_{SS} level "L", no matter what values in the shift registers , the LCD drive output pins ($Y_1 \sim Y_{120}$) are set to level V_5 . • When set to "L", the contents of the shift register are reset to not reading data. When the $\overline{DISPOFF}$ function is canceled, the driver outputs non-select level (V_1 or V_4),and the shift data is read at the next falling edge of the CK. At that time, if $\overline{DISPOFF}$ removal time does not correspond to what is shown in AC characteristics, the shift data is not read correctly. • See also Table 4. .

Pin Description (Continued)

Symbol	Function
FR	AC signal input pin for LCD drive waveform. See also Table 4. <ul style="list-style-type: none"> The input signal is level-shifted from logic voltage level to LCD drive voltage level, and controls the LCD drive circuit. Normally it inputs a frame inversion signal. The LCD drive output pins' output voltage levels can be set using the shift register output signal and the FR signal.
MODE	Mode selection input pin. See also Table 5. . <ul style="list-style-type: none"> When set to V_{SS} level "L", single mode is selected; when set to V_{DD} level "H", dual mode is selected.
DMIN	Dual mode data input pin. See also Table 5. . <ul style="list-style-type: none"> According to the data shift direction of the data shift register, data can be input starting from the 61th bit. When the chip is used in dual mode, DMIN will be pulled down. When the chip is used in single mode, DMIN won't be pulled down.
Y_1 - Y_{120}	LCD driver output pins. See also Table 4. <ul style="list-style-type: none"> According to each bit of the shift register, one level(V_0, V_1, V_4, or V_5) is selected and output to LCD panel.

Table 4. Logic data to output TRUTH TABLE

FR	Latch Data	$\overline{\text{DISPOFF}}$	Driver Output Voltage Level(Y_1 - Y_{120})
L	L	H	V_4
L	H	H	V_0
H	L	H	V_1
H	H	H	V_5
X	X	L	V_5

Notes:

- $V_{SS} \leq V_5 < V_4 < V_1 < V_0$, H: V_{DD} (+2.5 to +5.5V), X : Don't care
- "Don't care" means that the inputs should be connected to "H" or "L" Do not leave them open. There are two kinds of power supply (logic level voltage and LCD drive voltage) for the LCD driver. Supply regular voltage which is assigned by specification for each power pin.

Table 5. Relationship between the DATA I/O PINS and DATA TRANSFER DIRECTION

MODE	SHL	DATA TRANSFER DIRECTION	DIO ₁	DIO ₂	DMIN
L (Single)	L	$Y_1 \rightarrow Y_{120}$	Input	Output	X
	H	$Y_{120} \rightarrow Y_1$	Output	Input	X
H (Dual)	L	$Y_1 \rightarrow Y_{60}$	Input	Output	Input
		$Y_{61} \rightarrow Y_{120}$			
	H	$Y_{120} \rightarrow Y_{61}$	Output	Input	Input
		$Y_{60} \rightarrow Y_1$			

Notes:

- L : V_{SS} (0V), H : V_{DD} (+2.5 to +5.5V), X : Don't care.
- "Don't care" means that the inputs should be connected to "H" or "L" Do not leave them open.

Application Examples of Multiple Common Drives

(a) Single Mode (SHL= "L")

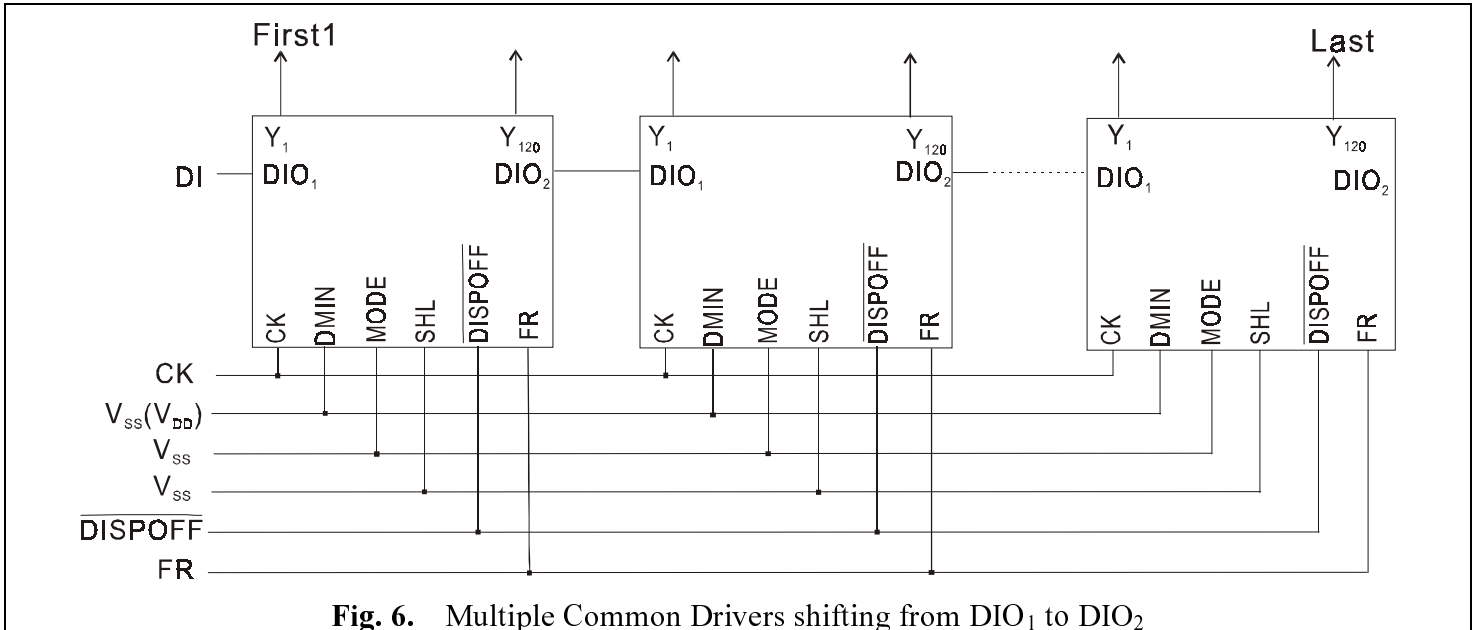


Fig. 6. Multiple Common Drivers shifting from DIO₁ to DIO₂

(b) Single Mode (SHL= "H")

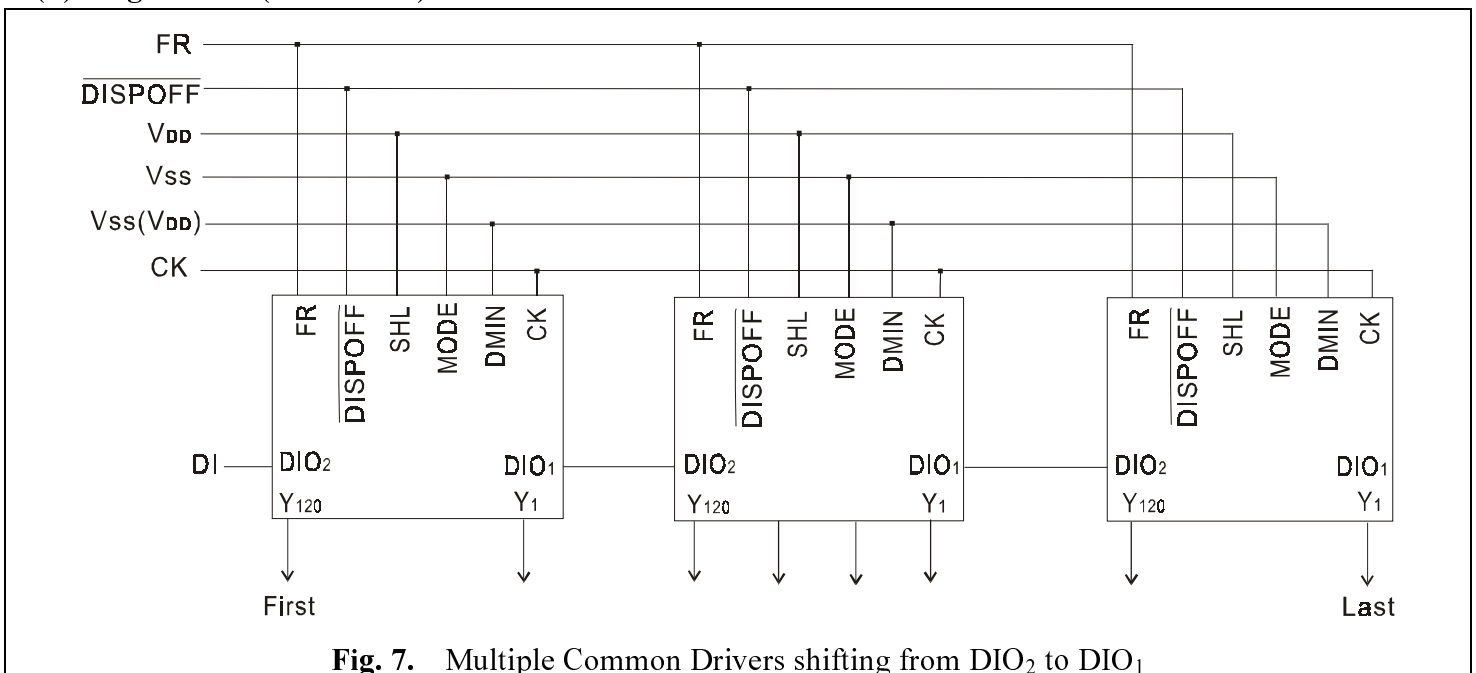
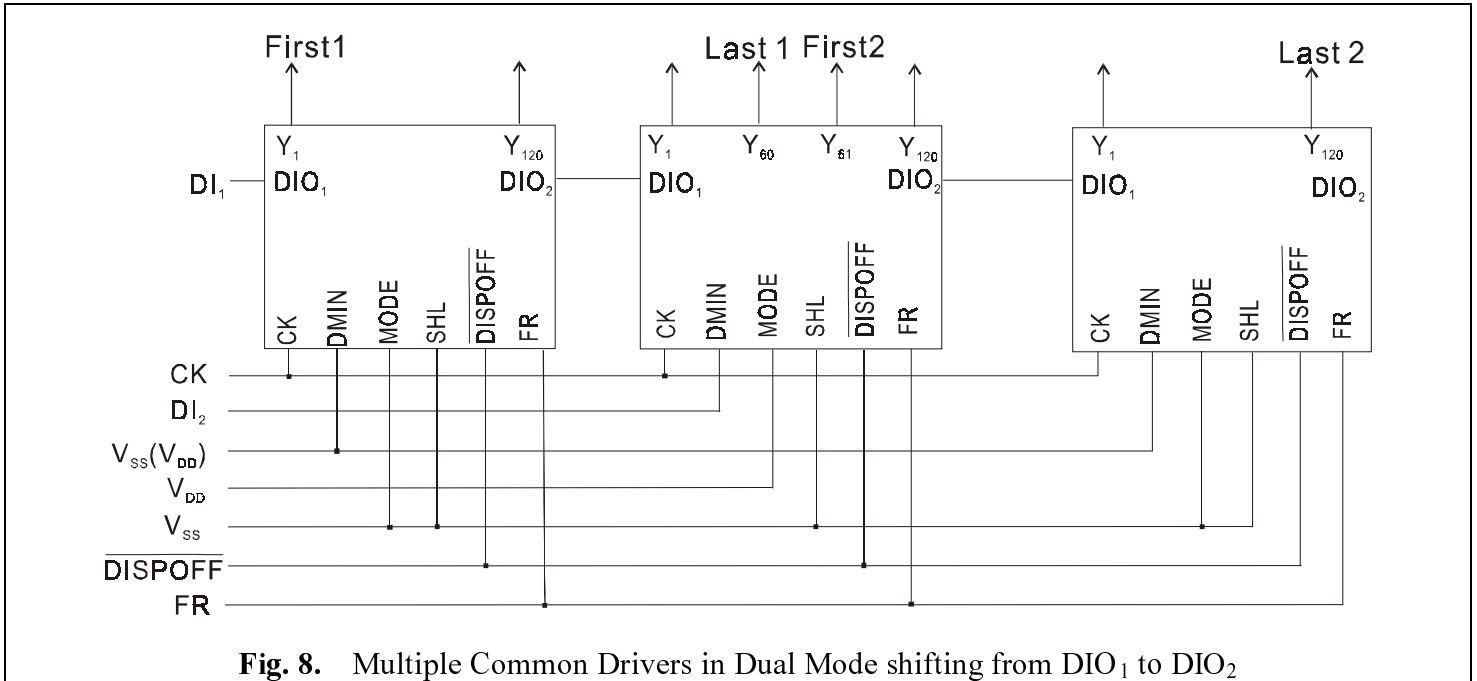
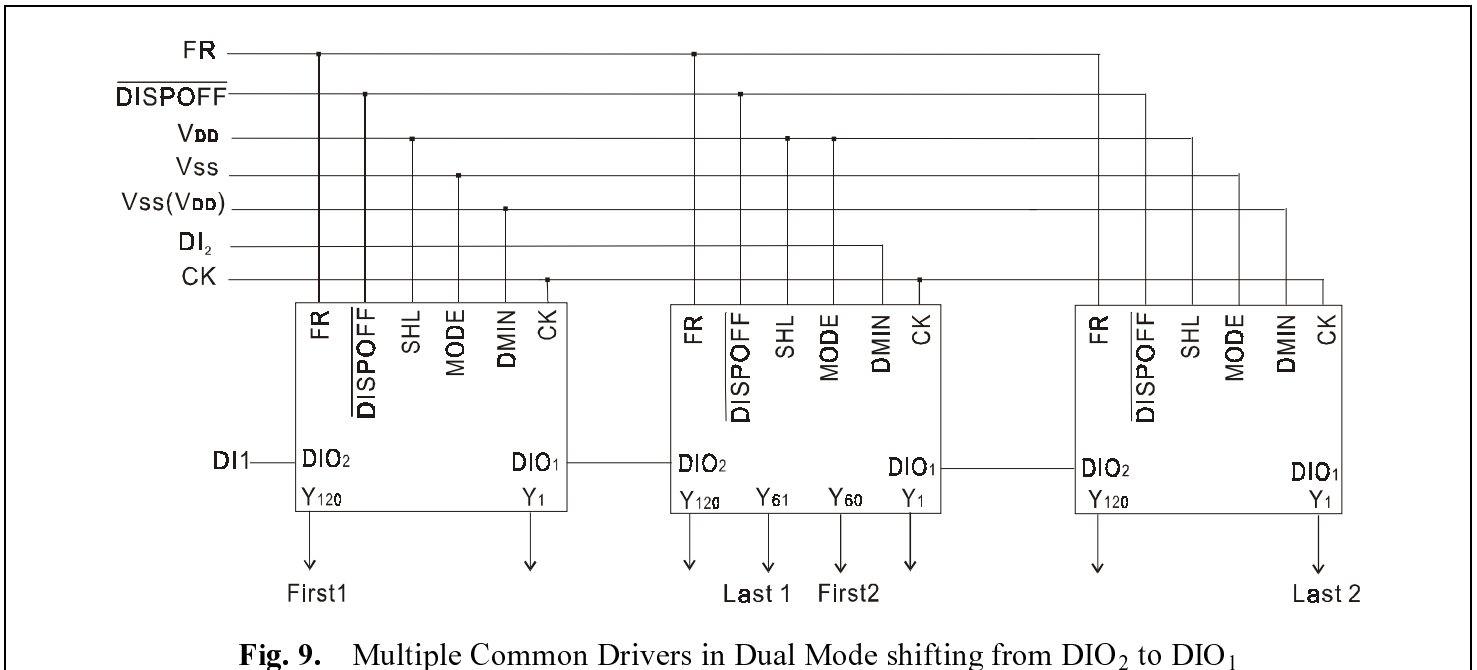


Fig. 7. Multiple Common Drivers shifting from DIO₂ to DIO₁

(c) Dual Mode (SHL= "L")



(c) Dual Mode (SHL= "H")



PRECAUTIONS

Precaution when connecting or disconnecting the power supply

This IC has a high-voltage LCD driver, so it may be permanently damaged by a high current which may flow if voltage is supplied to the LCD driver power supply while the logic system power supply is floating. The detail is as follows.

- When connecting the power supply, connect the LCD drive power after connecting the logic system power. Furthermore, when disconnecting the power, disconnect the logic system power after disconnecting the LCD drive power.
- It is advisable to connect the serial resistor (50 to 100 Ω) or fuse to the LCD drive power V_0 of the system as a current limiter. Set up a suitable value of the resistor in consideration of the display grade.

And when connecting the logic power supply, the logic condition of this IC inside is insecure. Therefore connect the LCD drive power supply after resetting logic condition of this IC inside on $\overline{\text{DISPOFF}}$ function. After that, cancel the $\overline{\text{DISPOFF}}$ function after the LCD drive power supply has become stable. Furthermore, when disconnecting the power, set the LCD drive output pins to level V_5 on $\overline{\text{DISPOFF}}$ function. Then disconnect the logic system power after disconnecting the LCD drive power.

When connecting the power supply, follow the recommended sequence shown here.

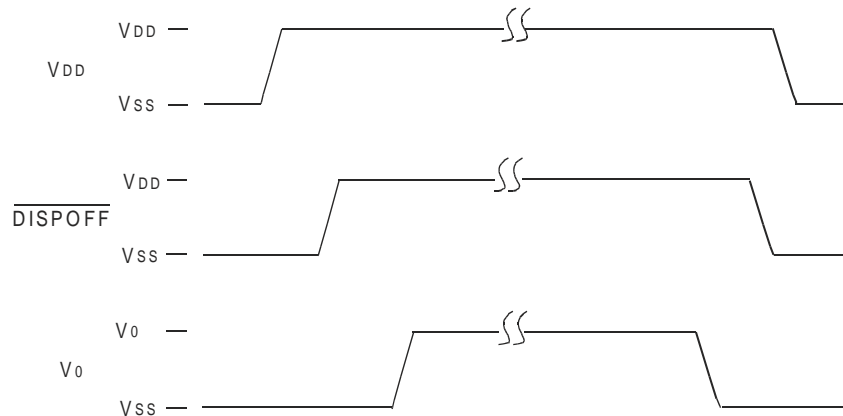


Fig. 10. Power Supply connecting sequence

ABSOLUTE MAXIMUM RATINGS

Table 6. Absolute maximum Ratings

In accordance with the Absolute Maximum Ratings System (IEC 134); See notes 1 and 2

Parameter	Symbol	Applicable Pins	Ratings	Unit	NOTE
Supply voltage(1)	V_{DD}	V_{DD}	-0.3 to +7.0	V	1, 2
Supply voltage(2)	V_0	V_{0L}, V_{0R}	-0.3 to +45.0	V	
	V_1	V_{1L}, V_{1R}	-0.3 to $V_0+0.3$	V	
	V_4	V_{4L}, V_{4R}	-0.3 to $V_0+0.3$	V	
	V_5	V_{5L}, V_{5R}	-0.3 to $V_0+0.3$	V	
Input voltage	V_1	DIO ₁ , DIO ₂ , CK, DMIN, SHL, MODE, FR, $\overline{\text{DISPOFF}}$	-0.3 to $V_{DD}+0.3$	V	
Storage temperature	T_{stg}		-45 to +125	°C	

Notes:

1. Stress above those listed under Absolute Maximum Ratings may cause permanent damage to the device
2. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

RECOMMENDED OPERATING CONDITIONS

Table 7. Recommended operating conditions

Parameter	Symbol	Applicable pins	Min.	Typ.	Max.	Unit	NOTE
Supply voltage(1)	V_{DD}	V_{DD}	+2.5		+5.5	V	1, 2
Supply voltage(2)	V_0	V_{0L}, V_{0R}	+15.0		+42.0	V	
Operating temperature	T_{OPR}		-20		+85	°C	

Notes:

1. All voltages are with respect to V_{SS} unless otherwise noted (0 V).
2. Ensure that voltages are set such that $V_{SS} \leq V_5 < V_4 < V_1 < V_0$.

ELECTRICAL CHARACTERISTICS

Table 8. DC Characteristics

($V_{SS}=V_5=0$ V, $V_{DD}=+2.5$ V to $+5.5$ V, $V_0=+15.0$ to $+40.0$ V, $T_{OPR}=-20$ to $+85^{\circ}$ C)

Parameter	Symbol	Conditions	Applicable pins	Min.	Typ.	Max.	Unit	NOTE	
Input “Low” voltage	V_{IL}		DIO ₁ ,DIO ₂ ,CK,DMIN, SHL,MODE,FR, $\overline{DISPOFF}$			$0.2V_{DD}$	V		
Input “High” voltage	V_{IH}			$0.8V_{DD}$			V		
Output “Low” voltage	V_{OL}	$I_{OI}=+0.4$ mA	DIO ₁ ,DIO ₂			+0.4	V		
Output “High” voltage	V_{OH}	$I_{OH}=-0.4$ mA		$V_{DD}-0.4$			V		
Input leakage current	I_{LIL}	$V_I=V_{SS}$	DIO ₁ ,DIO ₂ ,CK,DMIN, SHL,MODE,FR, $\overline{DISPOFF}$			-10.0	μ A		
	I_{LIH}	$V_I=V_{DD}$	CK,SHL,MODE,FR, $\overline{DISPOFF}$			+10.0	μ A		
Input pull-down current	I_{PD}	$V_I=V_{DD}$	DIO ₁ ,DIO ₂ ,DMIN			100.0	μ A		
Output resistance	R_{ON}	$ \Delta V_{ON} $ = 0.5V	$V_0=+40.0$ V	Y ₁ -Y ₁₂₀		0.7	1.0	K Ω	
			$V_0=+30.0$ V			1.0	1.5		
			$V_0=+20.0$ V			1.5	2.0		
Standby current	I_{STB}		V_{SS}			50.0	μ A	1	
Supply current(1)	I_{DD}		V_{DD}			60.0	μ A	2	
Supply current(2)	I_0		V_{0L}, V_{0R}			120.0	μ A	2	

Notes:

1. $V_{DD}=+5.0$ V, $V_0=+40.0$ V, $V_I=V_{SS}$
2. $V_{DD}=+5.0$ V, $V_0=+40.0$ V, $f_{CK}=41.6$ kHz, $f_{FR}=80$ Hz, 1/480 duty operation, no-load.

Table 9. AC Characteristics

($V_{SS}=V_5=0$ V, $V_{DD}=+2.5$ V to $+5.5$ V, $V_0=+15.0$ V to $+40.0$ V, $T_{OPR}=-20$ to $+85^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Shift clock period	t_{CK}		250			ns
		$V_{DD}=+2.5$ to ± 4.5 V	330			ns
Shift clock "H" pulse width	t_{WCKH}	$V_{DD}=+5.0\pm 0.5$ V	15			ns
		$V_{DD}=+2.5$ to $+4.5$ V	30			ns
Data setup time	t_{SU}		30			ns
Data Hold time	t_H		50			ns
Input signal rise time	t_R				50	ns
Input signal fall time	t_F				50	ns
$\overline{\text{DISPOFF}}$ removal time	t_{SD}		100			ns
$\overline{\text{DISPOFF}}$ "L" pulse width	t_{WDL}		1.2			μs
Output delay time(1)	t_D	$C_L=15$ pF $V_{DD}=+5.0\pm 0.5$ V			170	ns
		$C_L=15$ pF $V_{DD}=+2.5$ to ± 4.5 V			250	ns
Output delay time(2)	t_{PD1}, t_{PD2}	$C_L=15$ pF			1.2	μs
Output delay time(3)	t_{PD3}	$C_L=15$ pF			1.2	μs

Timing Chart

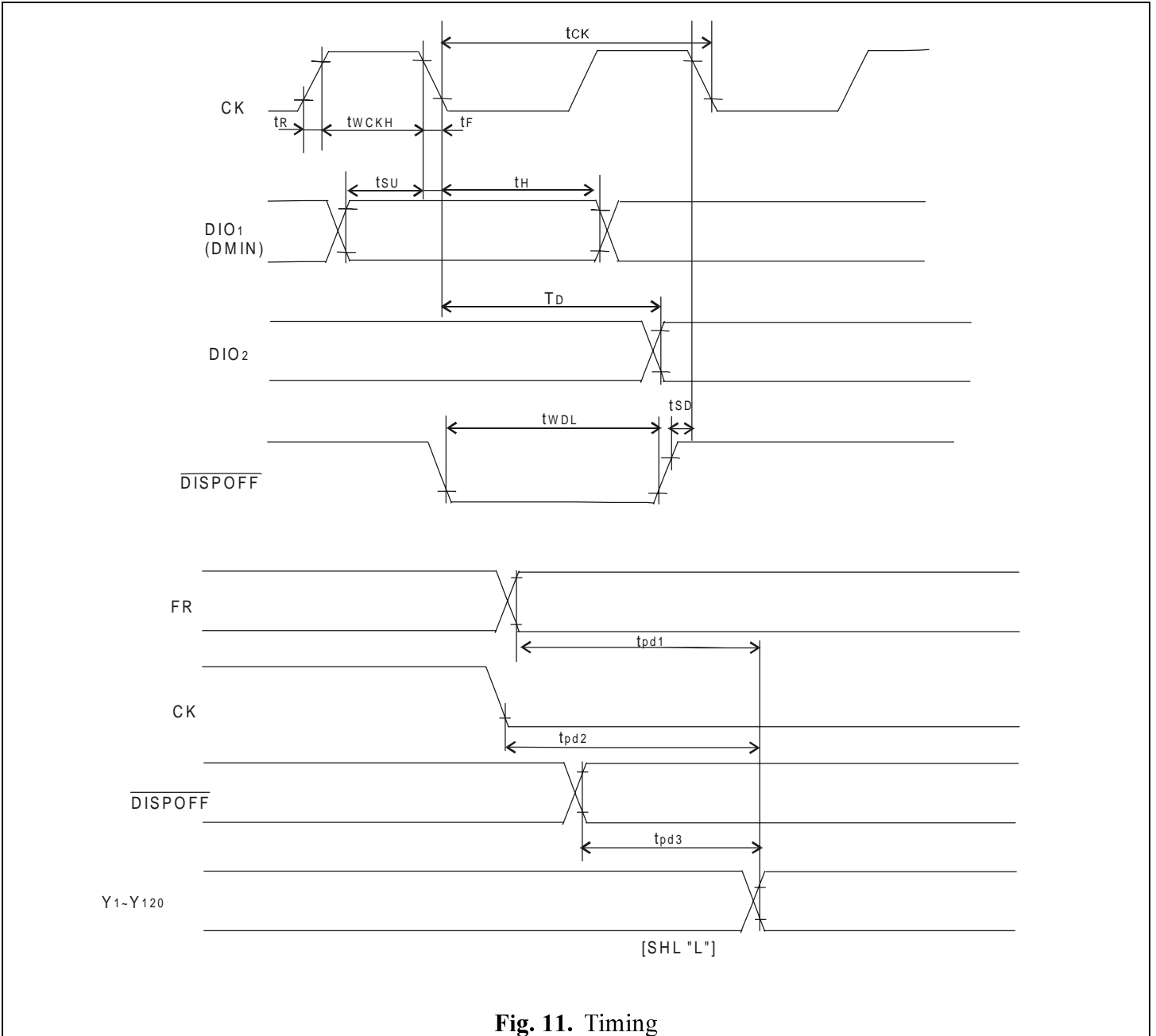
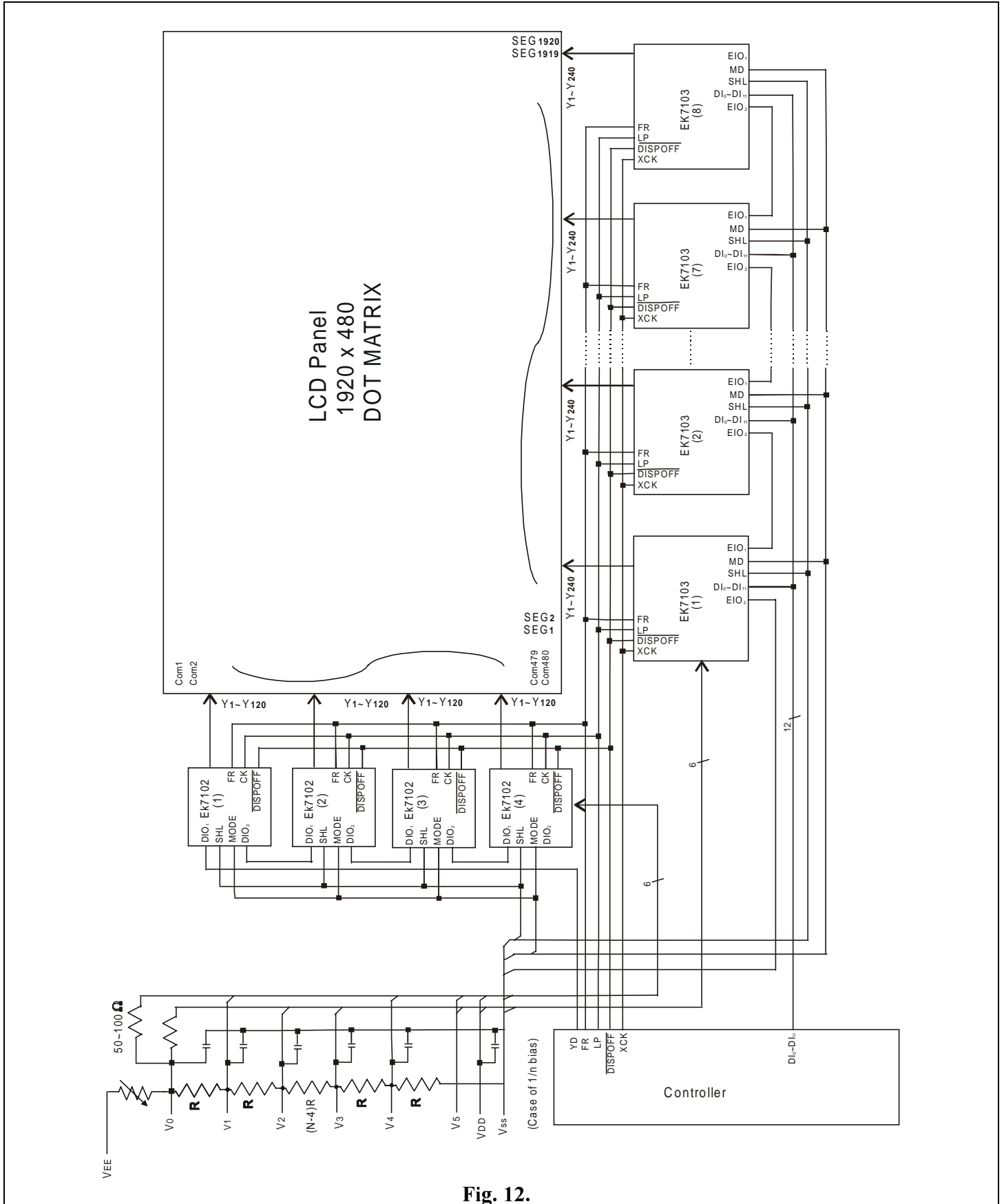


Fig. 11. Timing

SYSTEM CONFIGURATION EXAMPLE



ASSEMBLY INFORMATION

Chip Size : 7026 μ m x 1038 μ m

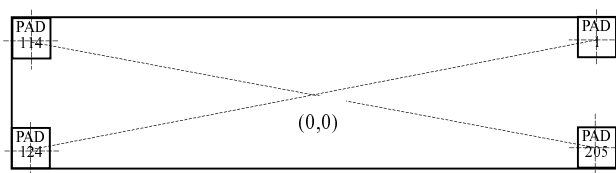
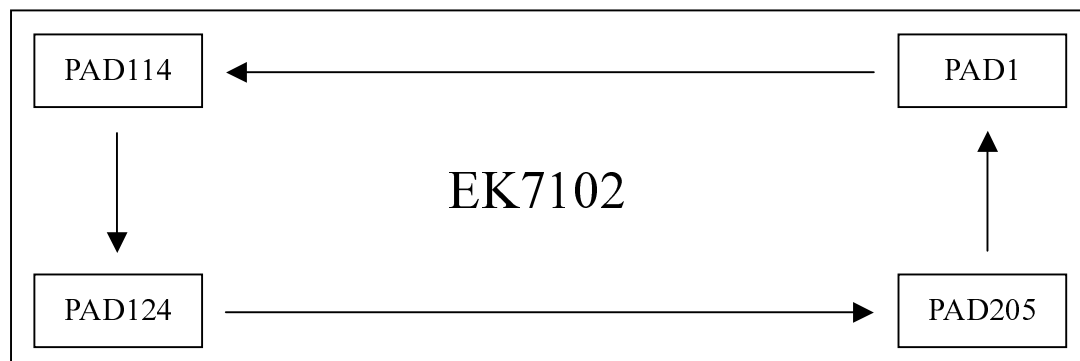


Fig. 1. Pad orientation and coordinate origin

Bump size (Unit : μ m)

Pad number	X	Y
1, 114, 124, 205	72.8	72.8
2 to 113	42.8	72.8
115 to 123	72.8	42.8
125 to 204	42.8	72.8
206 to 214	72.8	42.8

Bump specifications (reference values)

Items	Specifications	Note
Wafer thickness	483~533 μ m	
Bump size	$\pm 4\mu$ m	
Bump height	$18 \pm 3\mu$ m	within wafer < 4 μ m within die < 2 μ m
Bump strength (min.)	25g	

Notes:

1. All pads named Dummy are floating inside the chip and maybe used to aid routing on the glass.
2. In COG applications, the high voltage ground pad V_{GND} should have a separate path to the connector, and not be connected to V_{SS} on the glass. This is to prevent any ground bounce generated by high voltage switching to disturb the logic circuits.
3. Ensure that logic V_{SS} and high voltage V_{GND} are at the same potential.
4. Ensure that the Resistance to the high voltage supply pins is as low as possible.

Table 1 Pad coordinates (Bold face are corner pads)

PAD NO	Bump size	Pad Name	X-coordinate	Y-coordinate	Pad Size (µm)
PAD1	72.8X72.8	Y004	3405	411.3	85.2X85.2
PAD2	42.8X72.8	Y005	3330	411.3	55.2X85.2
PAD3	42.8X72.8	Y006	3270	411.3	55.2X85.2
PAD4	42.8X72.8	Y007	3210	411.3	55.2X85.2
PAD5	42.8X72.8	Y008	3150	411.3	55.2X 85.2
PAD6	42.8X72.8	Y009	3090	411.3	55.2X85.2
PAD7	42.8X72.8	Y010	3030	411.3	55.2X85.2
PAD8	42.8X72.8	Y011	2970	411.3	55.2X85.2
PAD9	42.8X72.8	Y012	2910	411.3	55.2X85.2
PAD10	42.8X72.8	Y013	2850	411.3	55.2X85.2
PAD11	42.8X72.8	Y014	2790	411.3	55.2X85.2
PAD12	42.8X72.8	Y015	2730	411.3	55.2X85.2
PAD13	42.8X72.8	Y016	2670	411.3	55.2X85.2
PAD14	42.8X72.8	Y017	2610	411.3	55.2X85.2
PAD15	42.8X72.8	Y018	2550	411.3	55.2X85.2
PAD16	42.8X72.8	Y019	2490	411.3	55.2X85.2
PAD17	42.8X72.8	Y020	2430	411.3	55.2X85.2
PAD18	42.8X72.8	Y021	2370	411.3	55.2X85.2
PAD19	42.8X72.8	Y022	2310	411.3	55.2X85.2
PAD20	42.8X72.8	Y023	2250	411.3	55.2X85.2
PAD21	42.8X72.8	Y024	2190	411.3	55.2X85.2
PAD22	42.8X72.8	Y025	2130	411.3	55.2X85.2
PAD23	42.8X72.8	Y026	2070	411.3	55.2X85.2
PAD24	42.8X72.8	Y027	2010	411.3	55.2X85.2
PAD25	42.8X72.8	Y028	1950	411.3	55.2X85.2
PAD26	42.8X72.8	Y029	1890	411.3	55.2X85.2
PAD27	42.8X72.8	Y030	1830	411.3	55.2X85.2
PAD28	42.8X72.8	Y031	1770	411.3	55.2X85.2
PAD29	42.8X72.8	Y032	1710	411.3	55.2X85.2
PAD30	42.8X72.8	Y033	1650	411.3	55.2X85.2
PAD31	42.8X72.8	Y034	1590	411.3	55.2X85.2
PAD32	42.8X72.8	Y035	1530	411.3	55.2X85.2
PAD33	42.8X72.8	Y036	1470	411.3	55.2X85.2
PAD34	42.8X72.8	Y037	1410	411.3	55.2X85.2
PAD35	42.8X72.8	Y038	1350	411.3	55.2X85.2

Table 2 Pad coordinates continued

PAD NO	Bump size	Pad Name	X-coordinate	Y-coordinate	Pad Size (µm)
PAD36	42.8X72.8	Y039	1290	411.3	55.2X 85.2
PAD37	42.8X72.8	Y040	1230	411.3	55.2X85.2
PAD38	42.8X72.8	Y041	1170	411.3	55.2X85.2
PAD39	42.8X72.8	Y042	1110	411.3	55.2X85.2
PAD40	42.8X72.8	Y043	1050	411.3	55.2X85.2
PAD41	42.8X72.8	Y044	990	411.3	55.2X85.2
PAD42	42.8X72.8	Y045	930	411.3	55.2X85.2
PAD43	42.8X72.8	Y046	870	411.3	55.2X85.2
PAD44	42.8X72.8	Y047	810	411.3	55.2X85.2
PAD45	42.8X72.8	Y048	750	411.3	55.2X85.2
PAD46	42.8X72.8	Y049	690	411.3	55.2X85.2
PAD47	42.8X72.8	Y050	630	411.3	55.2X85.2
PAD48	42.8X72.8	Y051	570	411.3	55.2X85.2
PAD49	42.8X72.8	Y052	510	411.3	55.2X85.2
PAD50	42.8X72.8	Y053	450	411.3	55.2X85.2
PAD51	42.8X72.8	Y054	390	411.3	55.2X85.2
PAD52	42.8X72.8	Y055	330	411.3	55.2X85.2
PAD53	42.8X72.8	Y056	270	411.3	55.2X85.2
PAD54	42.8X72.8	Y057	210	411.3	55.2X85.2
PAD55	42.8X72.8	Y058	150	411.3	55.2X85.2
PAD56	42.8X72.8	Y059	90	411.3	55.2X85.2
PAD57	42.8X72.8	Y060	30	411.3	55.2X85.2
PAD58	42.8X72.8	Y061	-30	411.3	55.2X85.2
PAD59	42.8X72.8	Y062	-90	411.3	55.2X85.2
PAD60	42.8X72.8	Y063	-150	411.3	55.2X85.2
PAD61	42.8X72.8	Y064	-210	411.3	55.2X85.2
PAD62	42.8X72.8	Y065	-270	411.3	55.2X85.2
PAD63	42.8X72.8	Y066	-330	411.3	55.2X85.2
PAD64	42.8X72.8	Y067	-390	411.3	55.2X85.2
PAD65	42.8X72.8	Y068	-450	411.3	55.2X85.2
PAD66	42.8X72.8	Y069	-510	411.3	55.2X85.2
PAD67	42.8X72.8	Y070	-570	411.3	55.2X85.2
PAD68	42.8X72.8	Y071	-630	411.3	55.2X85.2
PAD69	42.8X72.8	Y072	-690	411.3	55.2X85.2
PAD70	42.8X72.8	Y073	-750	411.3	55.2X85.2

Table 3 Pad coordinates continued

PAD NO	Bump size	Pad Name	X-coordinate	Y-coordinate	Pad Size (µm)
PAD71	42.8X72.8	Y074	-810	411.3	55.2X85.2
PAD72	42.8X72.8	Y075	-870	411.3	55.2X85.2
PAD73	42.8X72.8	Y076	-930	411.3	55.2X85.2
PAD74	42.8X72.8	Y077	-990	411.3	55.2X85.2
PAD75	42.8X72.8	Y078	-1050	411.3	55.2X85.2
PAD76	42.8X72.8	Y079	-1110	411.3	55.2X85.2
PAD77	42.8X72.8	Y080	-1170	411.3	55.2X85.2
PAD78	42.8X72.8	Y081	-1230	411.3	55.2X85.2
PAD79	42.8X72.8	Y082	-1290	411.3	55.2X85.2
PAD80	42.8X72.8	Y083	-1350	411.3	55.2X85.2
PAD81	42.8X72.8	Y084	-1410	411.3	55.2X85.2
PAD82	42.8X72.8	Y085	-1470	411.3	55.2X85.2
PAD83	42.8X72.8	Y086	-1530	411.3	55.2X85.2
PAD84	42.8X72.8	Y087	-1590	411.3	55.2X85.2
PAD85	42.8X72.8	Y088	-1650	411.3	55.2X85.2
PAD86	42.8X72.8	Y089	-1710	411.3	55.2X85.2
PAD87	42.8X72.8	Y090	-1770	411.3	55.2X85.2
PAD88	42.8X72.8	Y091	-1830	411.3	55.2X85.2
PAD89	42.8X72.8	Y092	-1890	411.3	55.2X85.2
PAD90	42.8X72.8	Y093	-1950	411.3	55.2X85.2
PAD91	42.8X72.8	Y094	-2010	411.3	55.2X85.2
PAD92	42.8X72.8	Y095	-2070	411.3	55.2X85.2
PAD93	42.8X72.8	Y096	-2130	411.3	55.2X85.2
PAD94	42.8X72.8	Y097	-2190	411.3	55.2X85.2
PAD95	42.8X72.8	Y098	-2250	411.3	55.2X85.2
PAD96	42.8X72.8	Y099	-2310	411.3	55.2X85.2
PAD97	42.8X72.8	Y100	-2370	411.3	55.2X85.2
PAD98	42.8X72.8	Y101	-2430	411.3	55.2X85.2
PAD99	42.8X72.8	Y102	-2490	411.3	55.2X85.2
PAD100	42.8X72.8	Y103	-2550	411.3	55.2X85.2
PAD101	42.8X72.8	Y104	-2610	411.3	55.2X85.2
PAD102	42.8X72.8	Y105	-2670	411.3	55.2X85.2
PAD103	42.8X72.8	Y106	-2730	411.3	55.2X85.2
PAD104	42.8X72.8	Y107	-2790	411.3	55.2X85.2
PAD105	42.8X72.8	Y108	-2850	411.3	55.2X85.2

Table 4 Pad coordinates continued

PAD NO	Bump size	Pad Name	X-coordinate	Y-coordinate	Pad Size (µm)
PAD106	42.8X72.8	Y109	-2910	411.3	55.2X85.2
PAD107	42.8X72.8	Y110	-2970	411.3	55.2X85.2
PAD108	42.8X72.8	Y111	-3030	411.3	55.2X85.2
PAD109	42.8X72.8	Y112	-3090	411.3	55.2X85.2
PAD110	42.8X72.8	Y113	-3150	411.3	55.2X85.2
PAD111	42.8X72.8	Y114	-3210	411.3	55.2X85.2
PAD112	42.8X72.8	Y115	-3270	411.3	55.2X85.2
PAD113	42.8X72.8	Y116	-3330	411.3	55.2X85.2
PAD114	72.8X72.8	Y117	-3405	411.3	85.2X85.2
PAD115	42.8X72.8	Y118	-3405	232.5	55.2X85.2
PAD116	42.8X72.8	Y119	-3405	172.5	55.2X85.2
PAD117	42.8X72.8	Y120	-3405	112.5	55.2X85.2
PAD118	42.8X72.8	V0L	-3405	52.5	55.2X85.2
PAD119	42.8X72.8	V0L	-3405	-7.5	55.2X85.2
PAD120	42.8X72.8	V1L	-3405	-67.5	55.2X85.2
PAD121	42.8X72.8	V4L	-3405	-127.5	55.2X85.2
PAD122	42.8X72.8	V5L	-3405	-187.5	55.2X85.2
PAD123	42.8X72.8	V5L	-3405	-247.5	55.2X85.2
PAD124	72.8X72.8	VGND	-3405	-411.3	85.2X85.2
PAD125	42.8X72.8	GND	-3330	-411.3	55.2X85.2
PAD126	42.8X72.8	GND	-3270	-411.3	55.2X85.2
PAD127	42.8X72.8	GND	-3210	-411.3	55.2X85.2
PAD128	42.8X72.8	Dummy	-3150	-411.3	55.2X85.2
PAD129	42.8X72.8	Dummy	-3090	-411.3	55.2X85.2
PAD130	42.8X72.8	Dummy	-3030	-411.3	55.2X85.2
PAD131	42.8X72.8	DIO_2	-2790	-411.3	55.2X85.2
PAD132	42.8X72.8	Dummy	-2670	-411.3	55.2X85.2
PAD133	42.8X72.8	Dummy	-2610	-411.3	55.2X85.2
PAD134	42.8X72.8	Dummy	-2550	-411.3	55.2X85.2
PAD135	42.8X72.8	Dummy	-2490	-411.3	55.2X85.2
PAD136	42.8X72.8	Dummy	-2430	-411.3	55.2X85.2
PAD137	42.8X72.8	Dummy	-2370	-411.3	55.2X85.2
PAD138	42.8X72.8	Dummy	-2310	-411.3	55.2X85.2
PAD139	42.8X72.8	Dummy	-2250	-411.3	55.2X85.2
PAD140	42.8X72.8	Dummy	-2190	-411.3	55.2X85.2

Table 5 Pad coordinates continued (Bold face are corner pads)

PAD NO	Bump size	Pad Name	X-coordinate	Y-coordinate	Pad Size (µm)
PAD141	42.8X72.8	FR	-2070	-411.3	55.2X85.2
PAD142	42.8X72.8	Dummy	-1950	-411.3	55.2X85.2
PAD143	42.8X72.8	Dummy	-1890	-411.3	55.2X85.2
PAD144	42.8X72.8	Dummy	-1830	-411.3	55.2X85.2
PAD145	42.8X72.8	Dummy	-1770	-411.3	55.2X85.2
PAD146	42.8X72.8	Dummy	-1710	-411.3	55.2X85.2
PAD147	42.8X72.8	Dummy	-1650	-411.3	55.2X85.2
PAD148	42.8X72.8	DISPOFF	-1350	-411.3	55.2X85.2
PAD149	42.8X72.8	Dummy	-1230	-411.3	55.2X85.2
PAD150	42.8X72.8	Dummy	-1170	-411.3	55.2X85.2
PAD151	42.8X72.8	Dummy	-1110	-411.3	55.2X85.2
PAD152	72.8X72.8	Dummy	-1050	-411.3	85.2X85.2
PAD153	42.8X72.8	Dummy	-990	-411.3	55.2X85.2
PAD154	42.8X72.8	Dummy	-930	-411.3	55.2X85.2
PAD155	42.8X72.8	Dummy	-870	-411.3	55.2X85.2
PAD156	42.8X72.8	Dummy	-810	-411.3	55.2X85.2
PAD157	42.8X72.8	Dummy	-750	-411.3	55.2X85.2
PAD158	42.8X72.8	SHL	-630	-411.3	55.2X85.2
PAD159	42.8X72.8	Dummy	-390	-411.3	55.2X85.2
PAD160	42.8X72.8	Dummy	-330	-411.3	55.2X85.2
PAD161	42.8X72.8	Dummy	-270	-411.3	55.2X85.2
PAD162	42.8X72.8	Dummy	-210	-411.3	55.2X85.2
PAD163	42.8X72.8	Dummy	-150	-411.3	55.2X85.2
PAD164	42.8X72.8	Dummy	-90	-411.3	55.2X85.2
PAD165	42.8X72.8	Dummy	90	-411.3	55.2X85.2
PAD166	42.8X72.8	MODE	210	-411.3	55.2X85.2
PAD167	42.8X72.8	Dummy	330	-411.3	55.2X85.2
PAD168	42.8X72.8	Dummy	390	-411.3	55.2X85.2
PAD169	42.8X72.8	Dummy	450	-411.3	55.2X85.2
PAD170	42.8X72.8	Dummy	510	-411.3	55.2X85.2
PAD171	42.8X72.8	Dummy	570	-411.3	55.2X85.2
PAD172	42.8X72.8	Dummy	630	-411.3	55.2X85.2
PAD173	42.8X72.8	Dummy	690	-411.3	55.2X85.2
PAD174	42.8X72.8	Dummy	750	-411.3	55.2X85.2
PAD175	42.8X72.8	Dummy	810	-411.3	55.2X85.2

Table 6 Pad coordinates continued

PAD NO	Bump size	Pad Name	X-coordinate	Y-coordinate	Pad Size (µm)
PAD176	42.8X72.8	DMIN	930	-411.3	55.2X85.2
PAD177	42.8X72.8	Dummy	1050	-411.3	55.2X85.2
PAD178	42.8X72.8	Dummy	1110	-411.3	55.2X85.2
PAD179	42.8X72.8	Dummy	1170	-411.3	55.2X85.2
PAD180	42.8X72.8	Dummy	1230	-411.3	55.2X85.2
PAD181	42.8X72.8	Dummy	1290	-411.3	55.2X85.2
PAD182	42.8X72.8	Dummy	1350	-411.3	55.2X85.2
PAD183	42.8X72.8	Dummy	1410	-411.3	55.2X85.2
PAD184	42.8X72.8	CK	1650	-411.3	55.2X85.2
PAD185	42.8X72.8	Dummy	1770	-411.3	55.2X85.2
PAD186	42.8X72.8	Dummy	1830	-411.3	55.2X85.2
PAD187	42.8X72.8	Dummy	1890	-411.3	55.2X85.2
PAD188	42.8X72.8	Dummy	1950	-411.3	55.2X85.2
PAD189	42.8X72.8	Dummy	2010	-411.3	55.2X85.2
PAD190	42.8X72.8	Dummy	2070	-411.3	55.2X85.2
PAD191	42.8X72.8	Dummy	2130	-411.3	55.2X85.2
PAD192	42.8X72.8	DIO_1	2370	-411.3	55.2X85.2
PAD193	42.8X72.8	Dummy	2490	-411.3	55.2X85.2
PAD194	42.8X72.8	Dummy	2550	-411.3	55.2X85.2
PAD195	42.8X72.8	Dummy	2610	-411.3	55.2X85.2
PAD196	42.8X72.8	Dummy	2670	-411.3	55.2X85.2
PAD197	42.8X72.8	Dummy	2730	-411.3	55.2X85.2
PAD198	42.8X72.8	VDD	2850	-411.3	55.2X85.2
PAD199	42.8X72.8	VDD	2910	-411.3	55.2X85.2
PAD200	42.8X72.8	VDD	2970	-411.3	55.2X85.2
PAD201	42.8X72.8	Dummy	3090	-411.3	55.2X85.2
PAD202	42.8X72.8	GND	3210	-411.3	55.2X85.2
PAD203	42.8X72.8	GND	3270	-411.3	55.2X85.2
PAD204	42.8X72.8	GND	3330	-411.3	55.2X85.2
PAD205	72.8X72.8	VGND	3405	-411.3	85.2X85.2
PAD206	42.8X72.8	V5R	3405	-247.5	55.2X85.2
PAD207	42.8X72.8	V5R	3405	-187.5	55.2X85.2
PAD208	42.8X72.8	V4R	3405	-127.5	55.2X85.2
PAD209	42.8X72.8	V1R	3405	-67.5	55.2X85.2
PAD210	42.8X72.8	V0R	3405	-7.5	55.2X85.2
PAD211	42.8X72.8	V0R	3405	52.5	55.2X85.2
PAD212	42.8X72.8	Y001	3405	112.5	55.2X85.2
PAD213	42.8X72.8	Y002	3405	172.5	55.2X85.2
PAD214	42.8X72.8	Y003	3405	232.5	55.2X85.2

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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